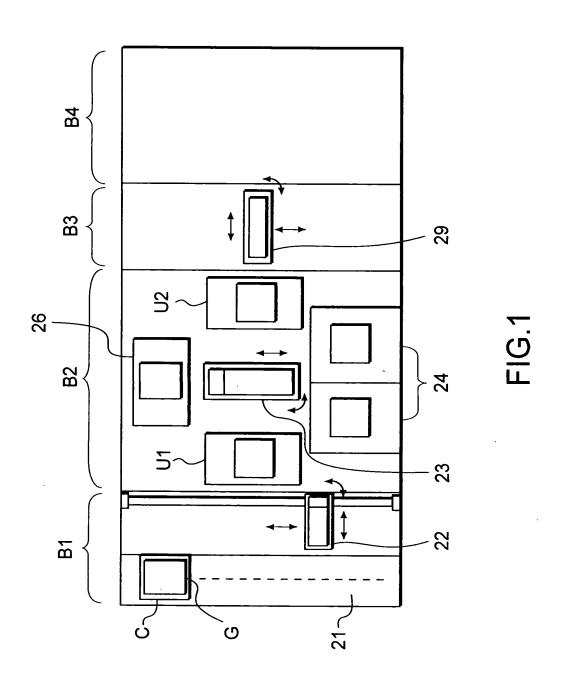
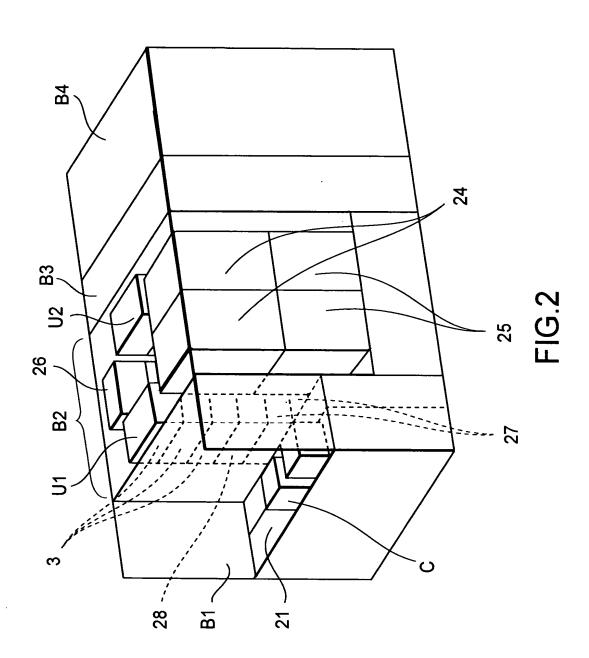
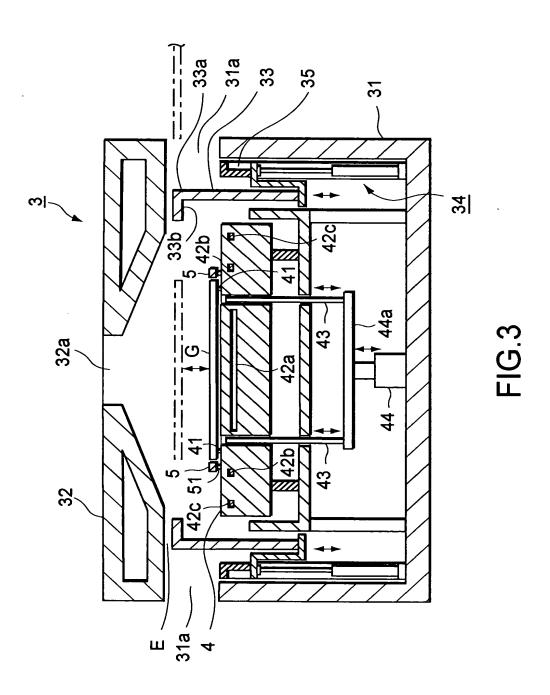
1/ 19





3/ 19



4/ 19 .

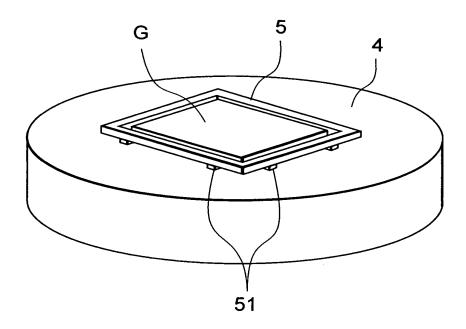


FIG.4

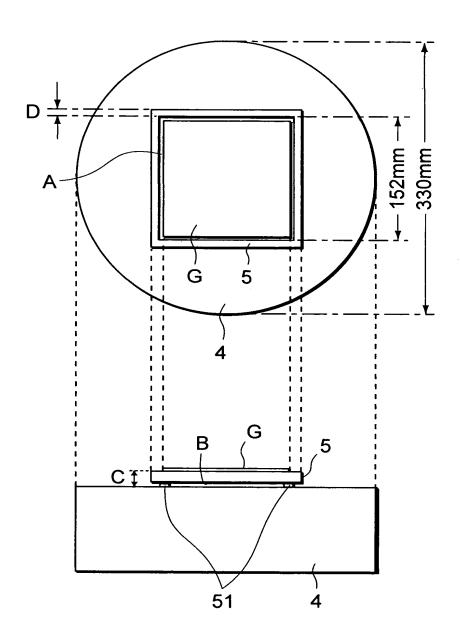


FIG.5

6/ 19

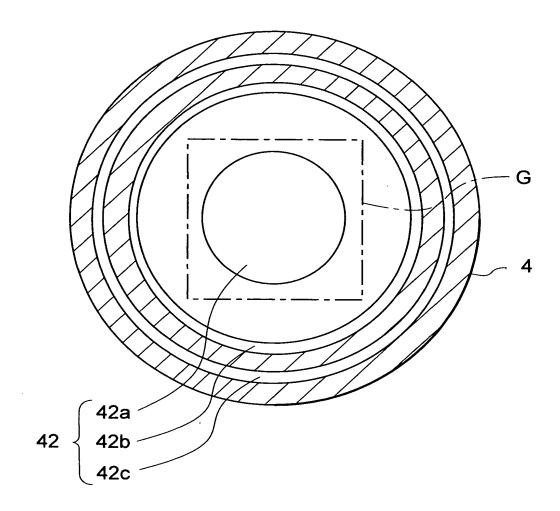


FIG.6

7/ 19

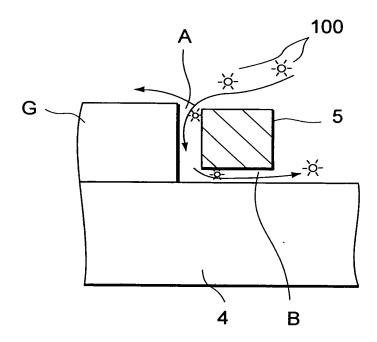


FIG.7

8/ 19

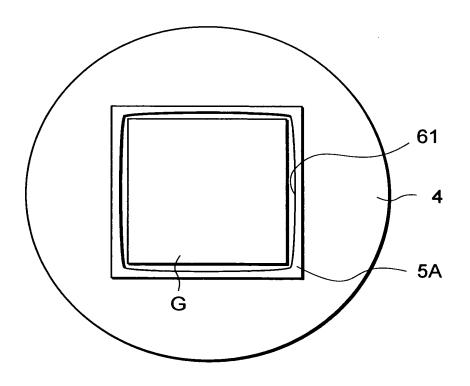


FIG.8A

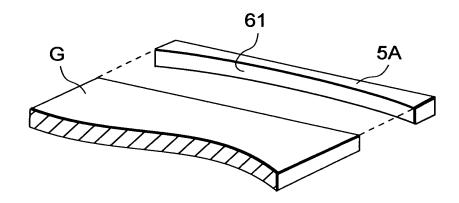


FIG.8B

OBLON, SPIVAK, ET AL DOCKET #: 248795US2 INV: Toshichika TAKEI, et al. SHEET 9_OF_19_

9/19

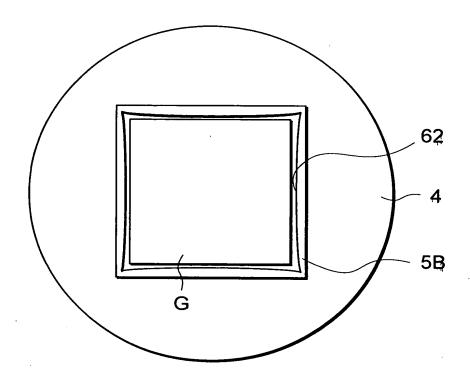


FIG.9A

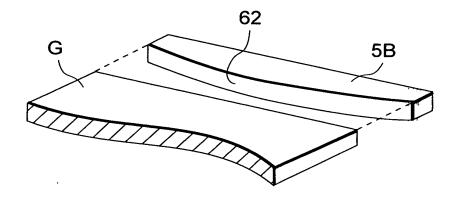


FIG.9B

10/19

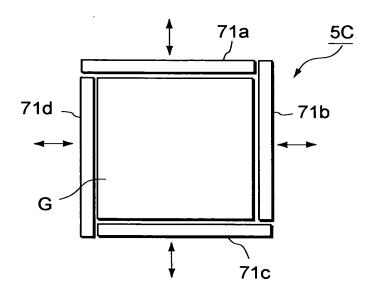


FIG.10A

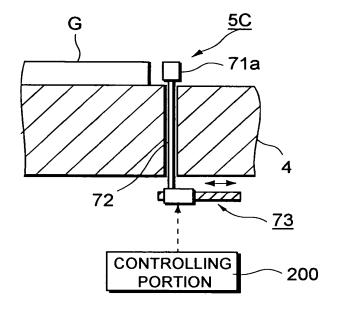


FIG.10B

11 / 19

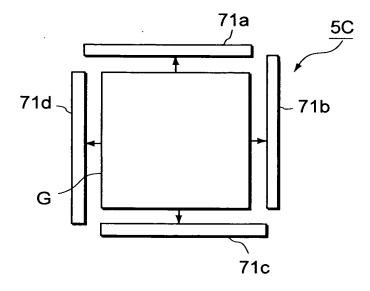


FIG.11A

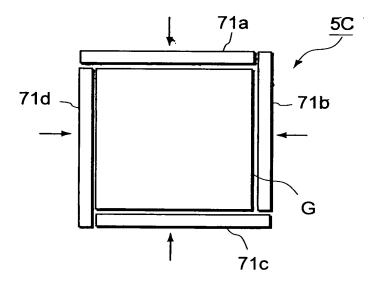


FIG.11B

12/ 19

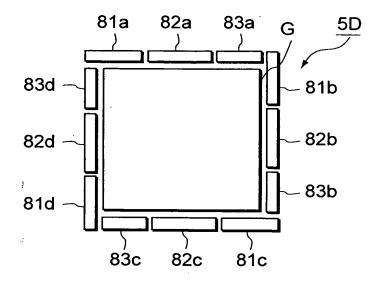


FIG.12A

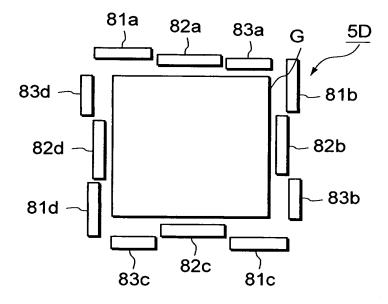


FIG.12B

OBLON, SPIVAK, ET AL DOCKET #: 248795US2 INV: Toshichika TAKEI, et al. SHEET 13 OF 19

13/19

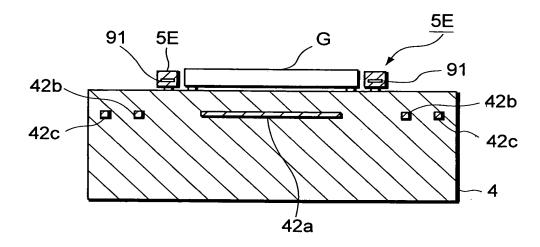
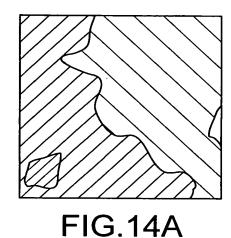


FIG.13

OBLON, SPIVAK, ET AL **DOCKET #: 248795US2** INV: Toshichika TAKEI, et al. SHEET <u>14</u> OF <u>19</u>

14/ 19

FIRST EXAMPLE (HEATING PLATE FOR 12-INCH SIZE WAFER, WITH FRAME MEMBER)



120.6 ~ 121℃

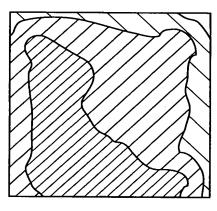
120.2 **~** 120.6℃

119.8 **~** 120.2℃

119.4 ~ 119.8℃

FIRST COMPARISON

(HEATING PLATE FOR 12-INCH SIZE WAFER, WITHOUT FRAME MEMBER)



119.0 ~ 119.4℃

FIG.14B

SECOND COMPARISON (HEATING PLATE FOR 8-INCH SIZE WAFER, WITHOUT FRAME MEMBER)

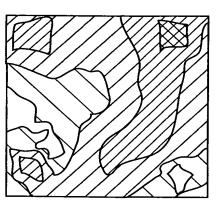


FIG.14C

15/19

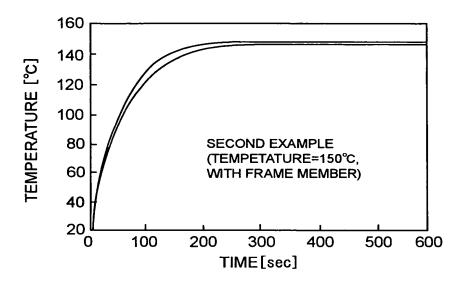


FIG.15A

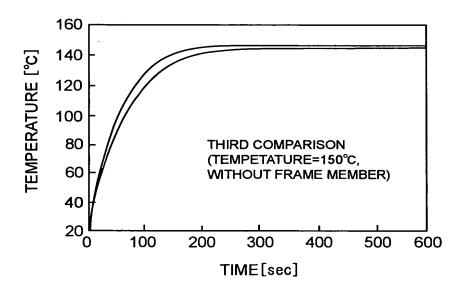


FIG.15B

16/19

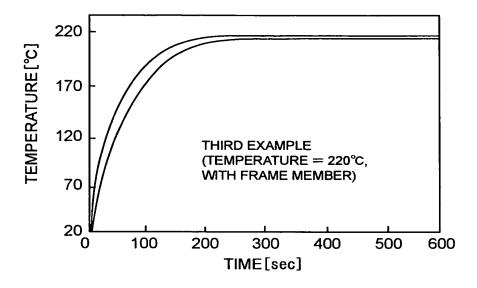


FIG.16A

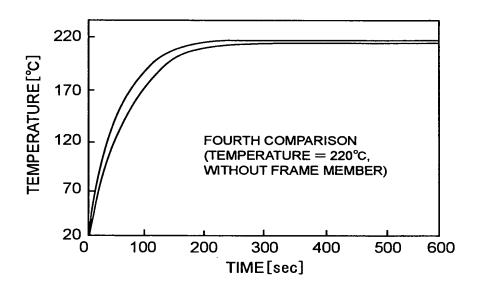


FIG.16B

17/ 19

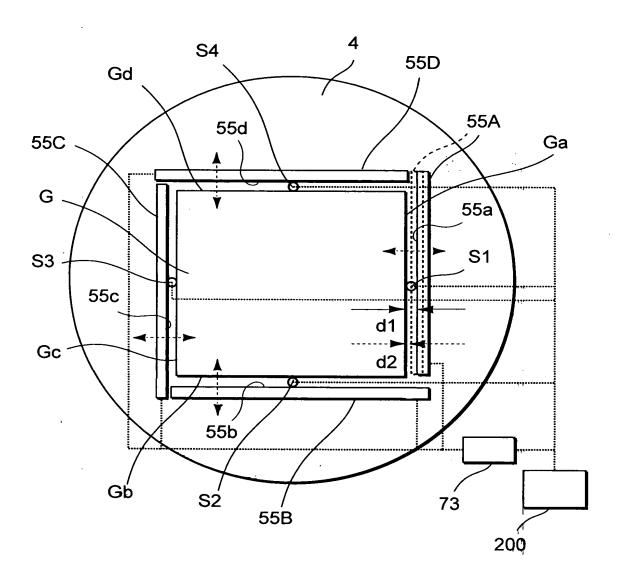


FIG.17

18/19

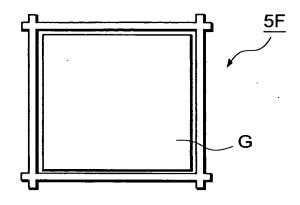


FIG.18A

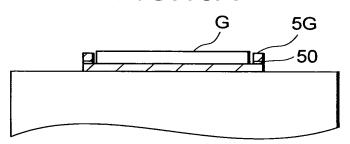


FIG.18B

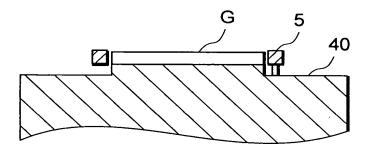


FIG.18C

PRIOR ART

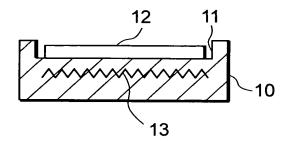


FIG.19

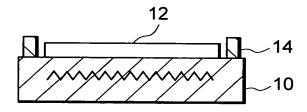


FIG.20

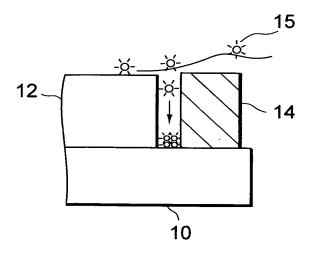


FIG.21